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Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Supplier		User Part Number					
Nexperia B.V. Name of Laboratory Assembly reliability labs Test		PESD5V0L1USF Part Description					
		BD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
			TEST Pre- and Post-Stress				
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
# F	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	15	1200	0	
# 5	Dias	Teverse voltage	1000 hours	15	1200	0	
# 7	TC Temperature Cycling	JESD22-A104 -40 °C to 125°C	1000 cycles	67	5360	0	
# 8	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	n.a.	n.a.	n.a.	
# 9	HAST Highly Accelerated Stress Test	JESD22-A110 Tamb = 130 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	1000 hours	67	5360	0	
# 10	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.	
# 20	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.	
# 21	SD Solderability	J-STD-002		12	120	0	

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM F	Protection INDI	1200	0	3.5	2.83E+08

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